

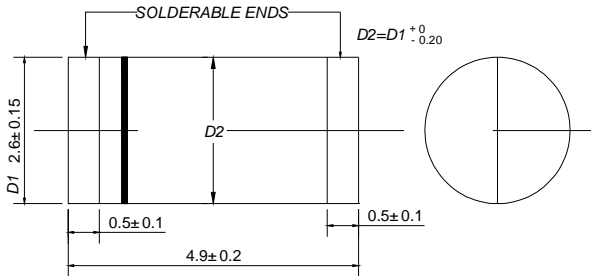


DLFR101 THRU DLFR107

SURFACE MOUNT RECTIFIERS

VOLTAGE RANGE : 50 --- 1000 V CURRENT: 1.0 A

DO - 213AB



Dimensions in millimeters

FEATURES

Plastic package has underwriters laboratories flammability classification 94V-0
Glass passivated chip junction
For surface mount applications
High temperature metallurgically bonded construction
Cavity-free glass passivated junction
High temperature soldering guaranteed: 450 °C / 5 seconds at terminals. Complete device submersible temperature of 265 °C for 10 seconds in solder bath

MECHANICAL DATA

Case: JEDEC DO-213AB, molded plastic
Terminals: Axial lead, solderable per MIL-STD-750, Method 2026
Polarity: Color band denotes cathode
Weight: 0.0046 ounces, 0.116 grams
Mounting position: Any

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25 °C ambient temperature unless otherwise specified.

Single phase, half wave, 60 Hz, resistive or inductive load. For capacitive load, derate current by 20%.

MDD CatalogNumber		DL FR101	DL FR102	DL FR103	DL FR104	DL FR105	DL FR106	DL FR107	UNITS
Maximum recurrent peak reverse voltage	V _{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V _{RMS}	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	V _{DC}	50	100	200	400	600	800	1000	V
Maximum average forward rectified current T _T =55	I _(AV)	1.0							A
Peak forward surge current 8.3ms single half-sine-wave superimposed on rated load (JEDEC Method)	I _{FSM}	30							A
Maximum instantaneous forward voltage @1.0A	V _F	1.3							V
Maximum reverse current @T _A =25 at rated DC blocking voltage @T _A =125	I _R	5.0 50							μA
Maximum reverse recovery time (Note 1)	t _{rr}	150				250	500		ns
Typical junction capacitance (Note 2)	C _j	15							pF
Typical thermal resistance (Note 3)	R _{θJA}	75							/W
Operating junction temperature range	T _j	- 55 ---- +175							
Storage temperature range	T _{STG}	- 55 ---- +175							

NOTE: 1. Measured with $I_F=0.5A$, $I_R=1.0A$, $t_{rr}=0.25A$

2. Measured at 1.0MHz and applied reverse voltage of 4.0V DC.

3. Thermal resistance from junction to ambient, 0.24x0.24" (6.0x6.0mm) copper pads to each terminal.

MDD ELECTRONIC

RATINGS AND CHARACTERISTIC CURVES DLFR101 THRU DLFR107

FIG.1 – FORWARD CURRENT DERATING CURVE

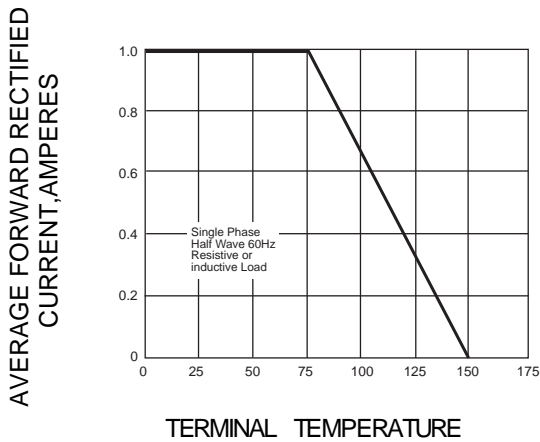
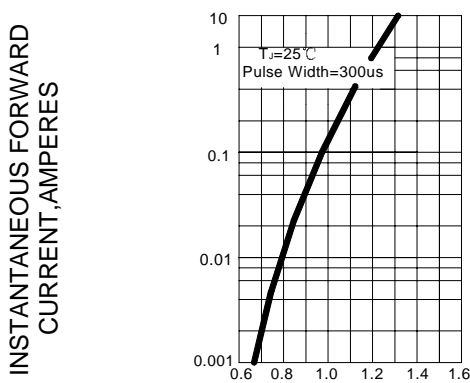


FIG.3 – TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS



INSTANTANEOUS FORWARD VOLTAGE(V)

FIG.5 – TYPICAL JUNCTION CAPACITANCE

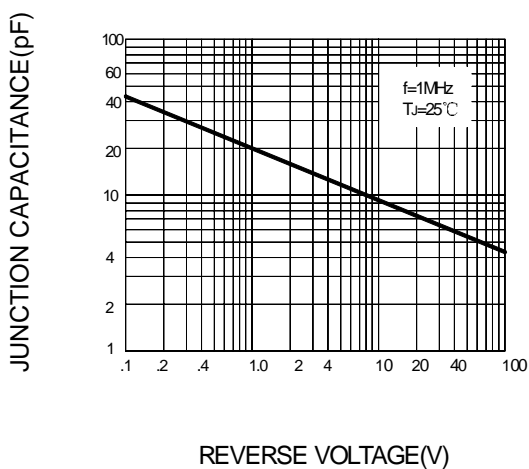


FIG.2 – MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

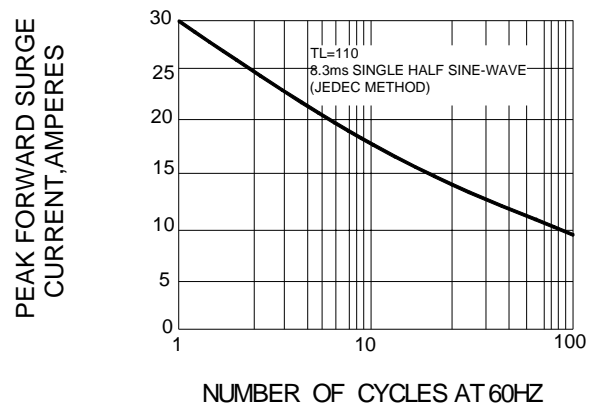
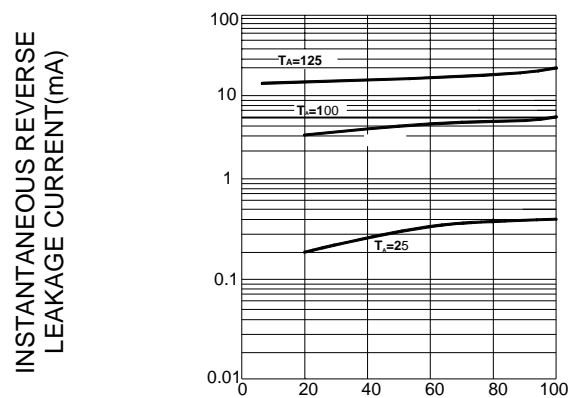


FIG.4 – TYPICAL REVERSE CHARACTERISTICS



PERCENT OF RATED PEAK REVERSE VOLTAGE. (%)

FIG.6 – TYPICAL TRANSIENT THERMAL IMPEDANCE

